

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	1	("6077357").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/29 10:37
L12	2634	(heat adj sink).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/29 11:27
L13	143	12 and (aluminum copper).ab.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/29 11:35
L14	0	12 and (aluminum copper).ab. and (electrostatic adj chuck)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/29 11:35
S1	3993	electrostatic adj chuck	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 12:08
S2	340	S1.ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 12:09
S3	397	(361/233).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:01
S4	22	kellerman-peter-l.in.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 15:27
S5	638	(361/234).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:24
S7	527	S5 and (temperature heat heating cool cooling)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:40
S8	472	S7 and semiconductor	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:47
S9	342	S8 and substrate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:27
S11	303	S9 and chuck	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:29
S12	312	S9 and (chuck clamp clamping clamps)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:42
S13	87	S12 and fluid	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:37
S14	86	S13 and (gas pressure)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:32
S15	292	S12 and (gas pressure)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:33
S16	67	S13 and silicon	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:37
S17	63	S16 and (layer layers)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:01
S18	397	(361/233).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:40
S19	176	S18 and (temperature heat heating cool cooling)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:40

S20	58	S19 and semiconductor	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:41
S21	64	S19 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:41
S22	37	S21 and (chuck clamp clamping clamps)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:42
S23	29	S22 and (layer layers)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:42
S24	640	(361/234).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:48
S25	529	S24 and (temperature heat heating cool cooling)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:47
S26	473	S25 and semiconductor	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:47
S27	473	S26 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 09:47
S28	9	(361/234).CCLS.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 09:50
S29	3	(361/233).CCLS.	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/22 09:50
S30	343	S26 and substrate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:01
S31	313	S30 and (chuck clamp clamping clamps)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:01
S32	87	S31 and fluid	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:01
S33	67	S32 and silicon	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:01
S34	63	S33 and (layer layers)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:01
S35	1	S34 and johnson.in.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:52
S36	2	((("3838204") or ("4234367")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:52
S37	12	("4184188" "4384918" "4502094" "4554611" "4645218" "4665463" "4692836" "4724510" "4796153" "4897171" "4962441" "5055964").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 10:56
S38	12	((("5103367") or ("5117121") or ("5325261") or ("5444597") or ("5452177") or ("5916689") or ("5958813") or ("6117246") or ("6149774") or ("6215643") or ("6236555") or ("6388861")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 12:21
S39	4	((("5583736") or ("5810933") or ("5838529") or ("6378600")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 12:22
S40	640	(361/234).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 16:48
S41	529	S40 and (temperature heat heating cool cooling)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 16:48

S42	473	S41 and semiconductor	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 16:48
S43	343	S42 and substrate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 16:48
S44	313	S43 and (chuck clamp clamping clamps)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 16:48
S45	87	S44 and fluid	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 16:48
S46	67	S45 and silicon	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 16:48
S47	63	S46 and (layer layers)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:14
S49	4	S46 not S47	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 16:52
S50	573	361/234.ccls. not S46	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:41
S51	397	(361/233).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:42
S52	176	S51 and (temperature heat heating cool cooling)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:42
S53	64	S52 and (semiconductor wafer)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:42
S54	321	361/233.ccls. not 361/234.ccls. not S53	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:47
S55	2	361/234.ccls. and (semiconductor adj platform)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:48
S56	479	361/234.ccls. and (semiconductor adj plate disc disk layer platform)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:49
S57	102	361/234.ccls. and (semiconductor with silicon)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:49
S58	102	361/234.ccls. and (semiconductor with silicon) and (semiconductor silicon adj platform disk disc plate layer level)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:50
S59	102	361/234.ccls. and ((semiconductor with silicon) same (semiconductor silicon adj platform disk disc plate layer level))	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 17:50
S60	640	(361/234).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:14
S61	529	S60 and (temperature heat heating cool cooling)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:14
S62	473	S61 and semiconductor	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:14
S63	343	S62 and substrate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:14
S64	313	S63 and (chuck clamp clamping clamps)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:14

S65	87	S64 and fluid	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:14
S66	67	S65 and silicon	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:14
S67	63	S66 and (layer layers)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 11:18
S68	63	S67 and (ceramic with semiconductor silicon rubber)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 11:18
S69	63	S67 and (ceramic near "7" semiconductor silicon rubber)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 12:03
S70	4183	electrostatic adj (clamp chuck)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 12:03
S71	13830	"2" same (semiconductor adj (layer platform))	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 12:04
S72	8	S70 same (semiconductor adj (layer platform))	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 12:20
S73	81	S70 and (semiconductor adj (layer platform))	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 12:04
S74	8	((("3518756") or ("3838204") or ("4080414") or ("4234367") or ("4430365") or ("4677254") or ("4799983"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 13:41
S75	27	kellerman-peter-l.in. or kellerman-peter-lawrence.in. or kellerman-peter.in.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/23 13:42
S76	19	("5103367" "5117121" "5325261" "5444597" "5452177" "5583736" "5810933" "5838529" "5916689" "5958813" "5969934" "6023405" "6067222" "6117246" "6149774" "6215643" "6236555" "6378600" "6388861").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 10:41
S78	1	("6721162").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 11:18
S79	640	(361/234).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 11:19
S80	529	S79 and (temperature heat heating cool cooling)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 11:19
S81	473	S80 and semiconductor	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 11:19
S82	343	S81 and substrate	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 11:19
S83	313	S82 and (chuck clamp clamping clamps)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 11:30
S84	120298	electrode with side	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 14:14
S85	700	S84 and (electrostatic adj chuck)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 14:14
S86	90	S84 and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 14:14

S87	78	S86 and electrodes and side	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 14:14
S88	21	S86 and electrodes with side	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 14:15
S89	0	S86 and electrodes with sidewall	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 14:15
S90	3107	spring with (side sidewall outer edge) with electrode\$1	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 14:48
S91	429	spring with (side sidewall outer edge) with electrode\$1 with force\$1	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 14:48
S92	5	S91 and "electrostatic chuck"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 16:02
S93	1	("5798475").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 16:02
S94	125	(electrostatic adj chuck) and (silicon adj dioxide) with insulat\$3	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 16:03
S95	73	(electrostatic adj chuck) and (silicon adj dioxide) with insulat\$3 with layer	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 16:04
S96	8	S95 and chuck.ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/26 16:04
S97	2790	pattern with "silicon dioxide"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 10:31
S98	19	S97 and "electrostatic chuck"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 10:52
S99	28270	"silicon dioxide" with (isolat\$3 insulat\$3 separat\$3 nonconduct\$3)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 10:53
S100	8313	S99 same (pole poles electrode electrodes positive negative polarity polarities polar charge)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 10:54
S101	1	S100 and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 10:56
S102	30	S100 and (electrostatic adj chuck)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:08
S103	229	"insulative insert"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:09
S104	1	S103 and "electrostatic chuck"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:09
S105	255	insert and "electrostatic chuck"	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:09
S106	36	insert and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:10
S107	74	"silicon nitride" and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:50
S108	1286337	"silicon nitride" same insulat\$3 protection isolat\$3 separat\$3 and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:51

S10 9	239	("silicon nitride" same insulat\$3 protection isolat\$3 separat\$3) and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:51
S11 0	239	((silicon adj nitride) same insulat\$3 protection isolat\$3 separat\$3) and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:52
S11 1	51344	(silicon adj nitride) same (insulat\$3 protection isolat\$3 separat\$3)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:53
S11 2	27	S111 and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 11:53
S11 3	2673	(surface adj roughness) with (micron microns micrometer micrometers um)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 12:29
S11 4	30	S113 and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/27 12:29
S11 5	16	(free adj molecular adj regime)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/29 10:37
S11 6	1	("4,184,188").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 11:38
S11 7	218	"mean free path" and (electrostatic adj chuck)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 11:38
S11 8	17	"mean free path" and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 11:38
S11 9	1	("6414834").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 16:37
S12 0	28270	"silicon dioxide" with (isolat\$3 insulat\$3 separat\$3 nonconduct\$3)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 16:24
S12 1	231	spring with forc\$3 with side with electrode\$1	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 16:39
S12 2	0	S121 and (electrostatic adj chuck)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 16:38
S12 3	1590416	spring springforced spring-forced with forc\$3 with side\$4 with electrode\$1	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 16:39
S12 4	288	(spring springforced spring-forced) with forc\$3 with side\$4 with electrode\$1	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 17:06
S12 5	17	S124 and chuck	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 16:40
S12 6	1454	spring with electrode with side	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 17:07
S12 7	0	S126 with (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 17:07
S12 8	0	S126 with (electrostatic adj chuck)	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 17:07
S12 9	1	S126 and (electrostatic adj chuck).ti.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 17:15
S13 0	25	ma-shawming.in.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 17:15